Product/Process Change Notice - PCN 10_0270 Rev. A

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

*** * * * * * * * ATTENTION: THIS PCN IS BEING CANCELLED! * * * * * * * ***

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title: Transfer to JCAP and Wafer Bumping Material Changes for ADATE209

Publication Date: 09-May-2014

Effectivity Date: Effective upon publication.

Revision Description:

ADI has cancelled plans to transfer the ADATE209 to Jiangyin Changdian Advanced Packaging Corp. (JCAP)

Description Of Change

Changes for ADATE209 are as follows:

Bumping Site
From STATSChipPAC Singapore; To Jiangyin Changdian Advanced Packaging Corp. (JCAP)

Flip Chip Bump on Die
From a Sn63/Pb37 bump; To a Sn95.5/Ag3.8/Cu0.7 Pb-free bump composition

Bump Process
From stencil printing; To preformed solder ball attach

Substrate Core Material
From CCL-HL-832; To DS-7409HGB

Substrate Prepreg Material
From GHPL-830HS; To DS-7409HG

Solder Mask Material
From PSR_4000_AUS-303; To PSR_4000_AUS-308

Reason For Change

ADI's existing subcontractor for wafer bumping has announced they are obsoleting their 6 inch capability. In order to maintain continuity of supply, ADI is transfering the affected products to JCAP for wafer bumping. ADI is also converting to Pb-free and Halogen free package materials. These materials have equivalent or improved properties and are not at risk to ongoing Environmental Legislation. ADI products using Pb-free bump alloys including Sn, Ag and Cu are mature.

Impact of the change (positive or negative) on fit, form, function & reliability

This change will not affect fit, form, function & reliability.

Summary of Supporting Information

Qualification will be performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Plan.

Supporting Documents

Attachment 1: Type: Qualification Plan Summary

ADI_PCN_10_0270_Rev_A_Qual Plan Summary .pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative					
Americas:	PCN_Americas@analog.com	**Europe:**	PCN_Europe@analog.com	**Japan:**	PCN_Japan@analog.com
				Rest of Asia:	PCN_ROA@analog.com

Appendix A - Affected ADI Models				
Existing Parts - Product Family / Model Number (1)				
ADATE209 / ADATE209BBCZ				

Appendix B - Revision History			
Rev	**Publish Date**	**Effectivity Date**	**Rev Description**
Rev. -	30-Sep-2010	28-Apr-2011	Initial Release
Rev. A	09-May-2014	09-May-2014	ADI has cancelled plans to transfer the ADATE209 to Jiangyin Changdian Advanced Packaging Corp. (JCAP)

Analog Devices, Inc. DocId:2882 Parent DocId:None Layout Rev:7